

## Four Output Differential Fanout Buffer for PCI Express Gen 1 & 2

ICS9DBL411

### Recommended Application:

PCI-Express fanout buffer

### Output Features:

- 4 - low power differential output pairs
- Individual OE# control of each output pair

### Key Specifications:

- Output cycle-cycle jitter < 25ps additive
- Output to output skew: < 50ps

### Features/Benefits:

- Low power differential fanout buffer for PCI-Express and CPU clocks
- 20-pin MLF or TSSOP packaging

### General Description:

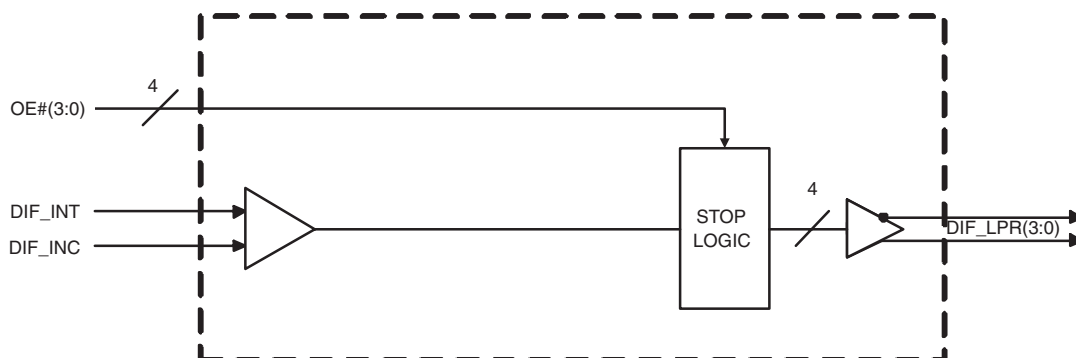
The **ICS9DBL411** is a 4 output lower power differential buffer. Each output has its own OE# pin. It has a maximum input frequency of 400 MHz.

### Power Groups

Pin Number (TSSOP)		Description
VDD	GND	
9,18	10,17	DIF(3:0)
4	5	Analog VDD & GND

Pin Number (MLF)		Description
VDD	GND	
6,15	7,14	DIF(3:0)
1	2	Analog VDD & GND

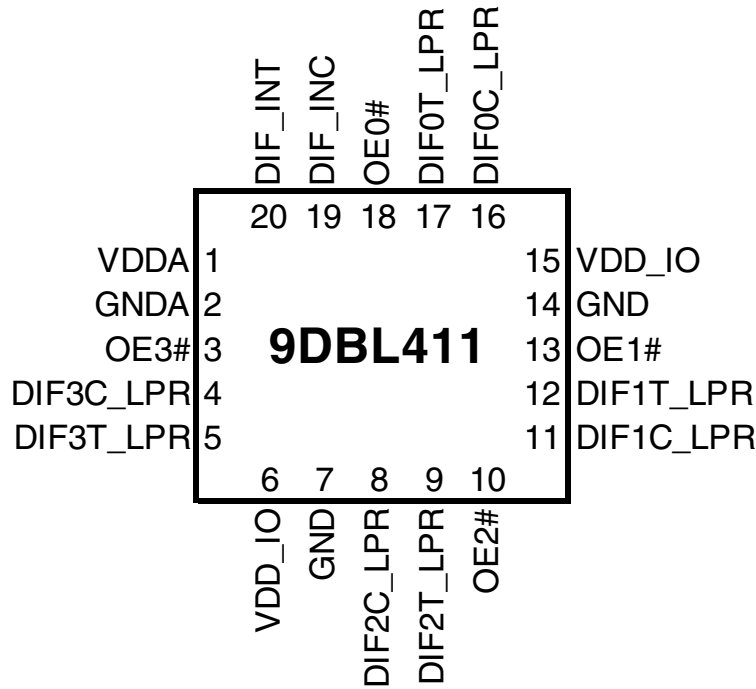
### Functional Block Diagram



## Pin Configuration

OE0#	1	<b>ICS9DBL411</b>	20	DIF0T_LPR
DIF_INC	2		19	DIF0C_LPR
DIF_INT	3		18	VDD_IO
VDDA	4		17	GND
GNDA	5		16	OE1#
OE3#	6		15	DIF1T_LPR
DIF3C_LPR	7		14	DIF1C_LPR
DIF3T_LPR	8		13	OE2#
VDD_IO	9		12	DIF2T_LPR
GND	10		11	DIF2C_LPR

**20-pin TSSOP**



**20-pin MLF**

## TSSOP Pin Description

PIN # (TSSOP)	PIN NAME	PIN TYPE	DESCRIPTION
1	OE0#	IN	Output Enable for DIF0 output. Control is as follows: 0 = enabled, 1 = Low-Low
2	DIF_INC	IN	Complement side of differential input clock
3	DIF_INT	IN	True side of differential input clock
4	VDDA	PWR	3.3V Power for the Analog Core
5	GND A	GND	Ground for the Analog Core
6	OE3#	IN	Output Enable for DIF3 output. Control is as follows: 0 = enabled, 1 = Low-Low
7	DIF3C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)
8	DIF3T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)
9	VDD_IO	PWR	Power supply for low power differential outputs, nominal 1.05V to 3.3V
10	GND	GND	Ground pin
11	DIF2C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)
12	DIF2T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)
13	OE2#	IN	Output Enable for DIF2 output. Control is as follows: 0 = enabled, 1 = Low-Low
14	DIF1C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)
15	DIF1T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)
16	OE1#	IN	Output Enable for DIF1 output. Control is as follows: 0 = enabled, 1 = Low-Low
17	GND	GND	Ground pin
18	VDD_IO	PWR	Power supply for low power differential outputs, nominal 1.05V to 3.3V
19	DIF0C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)
20	DIF0T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)

## MLF Pin Description

PIN # (MLF)	PIN NAME	PIN TYPE	DESCRIPTION
1	VDDA	PWR	3.3V Power for the Analog Core
2	GNDA	GND	Ground for the Analog Core
3	OE3#	IN	Output Enable for DIF3 output. Control is as follows: 0 = enabled, 1 = Low-Low
4	DIF3C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)
5	DIF3T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)
6	VDD_IO	PWR	Power supply for low power differential outputs, nominal 1.05V to 3.3V
7	GND	GND	Ground pin
8	DIF2C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)
9	DIF2T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)
10	OE2#	IN	Output Enable for DIF2 output. Control is as follows: 0 = enabled, 1 = Low-Low
11	DIF1C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)
12	DIF1T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)
13	OE1#	IN	Output Enable for DIF1 output. Control is as follows: 0 = enabled, 1 = Low-Low
14	GND	GND	Ground pin
15	VDD_IO	PWR	Power supply for low power differential outputs, nominal 1.05V to 3.3V
16	DIF0C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)
17	DIF0T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)
18	OE0#	IN	Output Enable for DIF0 output. Control is as follows: 0 = enabled, 1 = Low-Low
19	DIF_INC	IN	Complement side of differential input clock
20	DIF_INT	IN	True side of differential input clock

**Absolute Maximum Ratings**

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS	Notes
Maximum Supply Voltage	VDDxxx	Supply Voltage		4.6	V	1,7
Maximum Supply Voltage	VDDxxx_IO	Low-Voltage Differential I/O Supply	0.99	3.8	V	1,7
Maximum Input Voltage	V <sub>IH</sub>	3.3V LVCMOS Inputs		4.6	V	1,7,8
Minimum Input Voltage	V <sub>IL</sub>	Any Input	V <sub>SS</sub> - 0.5		V	1,7
Storage Temperature	T <sub>s</sub>	-	-65	150	°C	1,7
Input ESD protection	ESD prot	Human Body Model	2000		V	1,7

**Electrical Characteristics - Input/Supply/Common Output Parameters**

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS	Notes
Ambient Operating Temp	T <sub>ambient</sub>	-	0	70	°C	1
Supply Voltage	VDDxxx	Supply Voltage	3.135	3.465	V	1
Supply Voltage	VDDxxx_IO	Low-Voltage Differential I/O Supply	0.99	3.465	V	1
Input High Voltage	V <sub>IHSE</sub>	Single-ended inputs	2	V <sub>DD</sub> + 0.3	V	1
Input Low Voltage	V <sub>ILSE</sub>	Single-ended inputs	V <sub>SS</sub> - 0.3	0.8	V	1
Input High Voltage	V <sub>IHDIF</sub>	Differential inputs	600	1.15	V	1
Input Low Voltage	V <sub>ILDIF</sub>	Differential inputs	V <sub>SS</sub> - 0.3	300	V	1
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4	8	V/ns	2
Input Leakage Current	I <sub>IN</sub>	V <sub>IN</sub> = V <sub>DD</sub> , V <sub>IN</sub> = GND	-5	5	uA	1
Operating Supply Current	I <sub>DD_3.3V</sub>	3.3V supply		25	mA	1
	I <sub>DD_IO_100M</sub>	VDD_IO supply @ fOP = 100MHz		15	mA	1
	I <sub>DD_IO_400M</sub>	VDD_IO supply @ fOP = 400MHz		54	mA	1
Standby Current	I <sub>DD_SB33</sub>	3.3V supply, Input stopped		25	mA	1
	I <sub>DD_SBio</sub>	0.8V IO supply, Input stopped		0.1	mA	1
Input Frequency	F <sub>i</sub>	V <sub>DD</sub> = 3.3 V	33	400	MHz	2
Pin Inductance	L <sub>pin</sub>			7	nH	1
Input Capacitance	C <sub>IN</sub>	Logic Inputs	1.5	5	pF	1
	C <sub>OUT</sub>	Output pin capacitance		6	pF	1
OE# latency	T <sub>OE#LAT</sub>	Number of clocks to enable or disable output from assertion/deassertion of OE#	1	3	periods	1
Tdrive_OE#	T <sub>DROE#</sub>	Output enable after OE# de-assertion		10	ns	1
Tfall_OE#	T <sub>FALL</sub>	Fall/rise time of OE# inputs		5	ns	1
Trise_OE#	T <sub>RISE</sub>			5	ns	1

### AC Electrical Characteristics - DIF Low Power Differential Outputs

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS	NOTES
Rising Edge Slew Rate	$t_{SLR}$	Differential Measurement	1	2.5	V/ns	1,2
Falling Edge Slew Rate	$t_{FLR}$	Differential Measurement	1	2.5	V/ns	1,2
Slew Rate Variation	$t_{SLVAR}$	Single-ended Measurement		20	%	1
Maximum Output Voltage	$V_{HIGH}$	Includes overshoot		1150	mV	1
Minimum Output Voltage	$V_{LOW}$	Includes undershoot	-300		mV	1
Differential Voltage Swing	$V_{SWING}$	Differential Measurement	300		mV	1
Crossing Point Voltage	$V_{XABS}$	Single-ended Measurement	300	550	mV	1,3,4
Crossing Point Variation	$V_{XABSVAR}$	Single-ended Measurement		140	mV	1,3,5
Duty Cycle Distortion	$D_{CYCDIS1}$	Dif Measurement, $f_{IN} \leq 267\text{MHz}$		+5	%	1,6
	$D_{CYCDIS2}$	Dif Measurement, $f_{IN} > 267\text{MHz}$		+7	%	1,6
DIF Jitter - Cycle to Cycle	$DIFJ_{C2C}$	Differential Measurement, <b>Additive</b>		25	ps	1
DIF[3:0] Skew	$DIF_{SKEW}$	Differential Measurement		50	ps	1
Propagation Delay	$t_{PD}$	Input to output Delay	2.5	3.5	ns	1
PCIe Gen2 Phase Jitter - Additive	$t_{phase\_addHI}$	$1.5\text{MHz} < f_{IN} < \text{Nyquist} (50\text{MHz})$		0.8	ps rms	1
PCIe Gen2 Phase Jitter - Additive	$t_{phase\_addLO}$	$10\text{KHz} < f_{IN} < 1.5\text{MHz}$		0.1	ps rms	1

#### Notes on Electrical Characteristics:

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup>Slew rate measured through  $V_{swing}$  centered around differential zero

<sup>3</sup> $V_{xabs}$  is defined as the voltage where  $CLK = CLK\#$

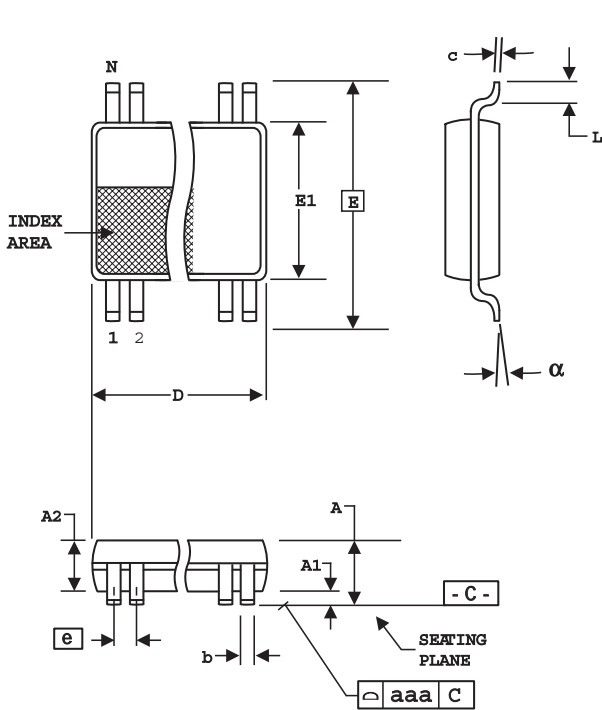
<sup>4</sup>Only applies to the differential rising edge (CLK rising and CLK# falling)

<sup>5</sup>Defined as the total variation of all crossing voltages of CLK rising and CLK# falling. Matching applies to rising edge rate of CLK and falling edge of CLK#. It is measured using a +/-75mV window centered on the average cross point where CLK meets CLK#.

<sup>6</sup>This is the figure refers to the maximum distortion of the input wave form.

<sup>7</sup>Operation under these conditions is neither implied, nor guaranteed.

<sup>8</sup>Maximum input voltage is not to exceed maximum VDD



20-Lead, 4.40 mm. Body, 0.65 mm. Pitch TSSOP  
(173 mil) (25.6 mil)

SYMBOL	In Millimeters		In Inches	
	COMMON DIMENSIONS	COMMON DIMENSIONS	COMMON DIMENSIONS	COMMON DIMENSIONS
A	--	1.20	--	.047
A1	0.05	0.15	.002	.006
A2	0.80	1.05	.032	.041
b	0.19	0.30	.007	.012
c	0.09	0.20	.0035	.008
D	SEE VARIATIONS		SEE VARIATIONS	
E	6.40 BASIC		0.252 BASIC	
E1	4.30	4.50	.169	.177
e	0.65 BASIC		0.0256 BASIC	
L	0.45	0.75	.018	.030
N	SEE VARIATIONS		SEE VARIATIONS	
a	0°	8°	0°	8°
aaa	--	0.10	--	.004

VARIATIONS

N	D mm.		D (inch)	
	MIN	MAX	MIN	MAX
20	6.40	6.60	.252	.260

Reference Doc.: JEDEC Publication 95, MO-153

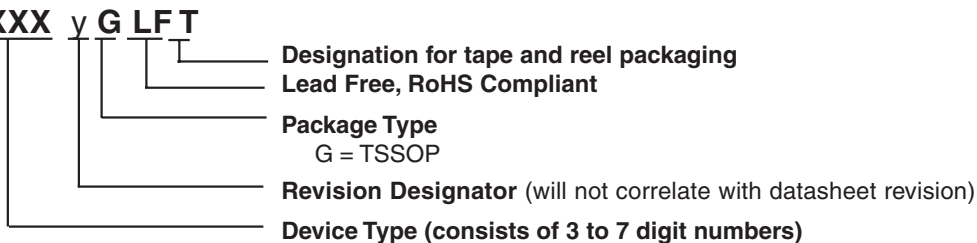
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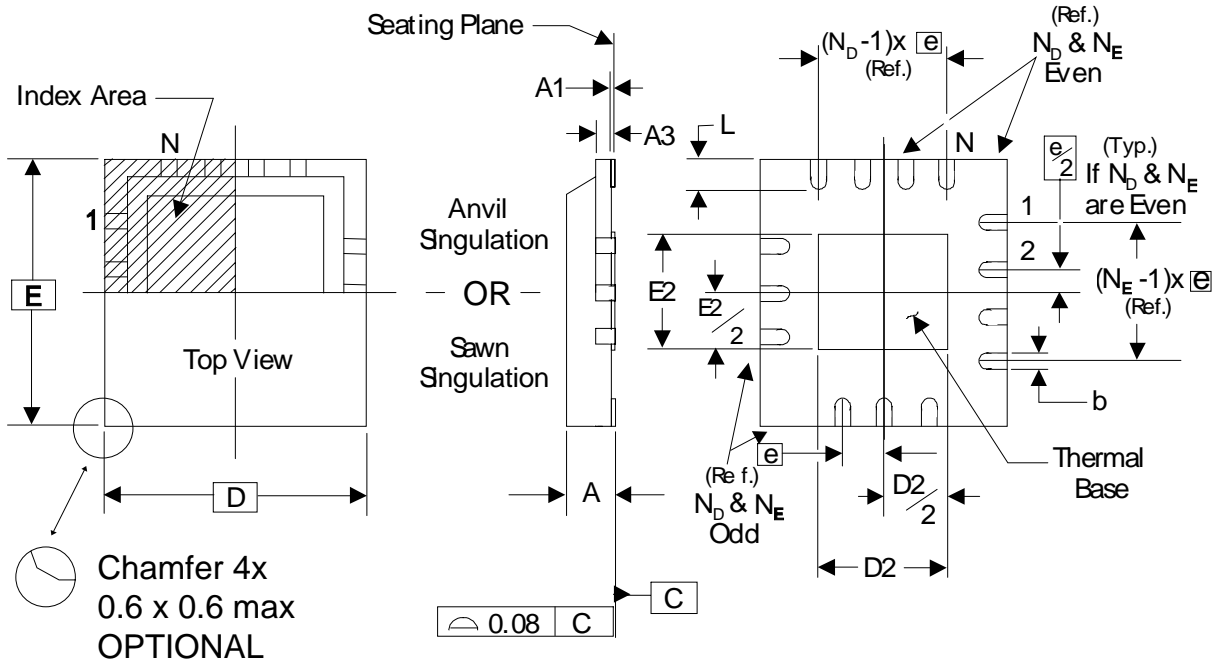
## Ordering Information

ICS 9DBL411yGLFT

Example:

ICS **XXXX** **y** **G** **LFT**





THERMALLY ENHANCED, VERY THIN, FINE PITCH  
QUAD FLAT / NO LEAD PLASTIC PACKAGE

DIMENSIONS

SYMBOL	MIN.	MAX.
A	0.8	1.0
A1	0	0.05
A3	0.20 Reference	
b	0.18	0.3
e	0.50 BASIC	

DIMENSIONS

SYMBOL	ICS 20L TOLERANCE
N	20
N <sub>D</sub>	5
N <sub>E</sub>	5
D x E BASIC	4.00 x 4.00
D2 MIN. / MAX.	2.00 / 2.25
E2 MIN. / MAX.	2.00 / 2.25
L MIN. / MAX.	0.45 / 0.65

## Ordering Information

### ICS 9DBL411yKLFT

Example:

ICS XXXX y K LFT

- \_\_\_\_\_ Designation for tape and reel packaging
- \_\_\_\_\_ Lead Free, RoHS Compliant
- \_\_\_\_\_ Package Type  
K = MLF
- \_\_\_\_\_ Revision Designator (will not correlate with datasheet revision)
- \_\_\_\_\_ Device Type (consists of 3 to 7 digit numbers)



**Revision History**

Rev.	Issue Date	Description	Page #
0.1	08/01/06	Initial Release.	-
0.2	09/22/06	Updated MLF Package Dimensions.	8
A	07/31/07	1. Updated electrical characteristics - additive jitter, cycle-to-cycle, tpd, skews, slew rates, Idd, etc. 2. Corrected power grouping table for TSSOP pkg 3. Final Release	1,5,6

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